

ABSTRACT OF THE DISCLOSURE

An integrated circuit interconnect module for reducing interconnections between integrated circuit chips MOUNTED ON a support substrate. At least one primary integrated circuit (IC) device chip and a plurality of interacting peripheral integrated chip devices. The interconnect module including a plurality of interface pins, each integrated circuit device having a plurality of interface ports. At least one interface port of which is connected to another one of said plurality of integrated circuit devices, at least one of said integrated circuit devices having an interface port connected to an interface pin whereby the majority of nodes on the interacting peripheral devices are adapted to interface with nodes of the primary IC devices in such a way as to condense the number of nets so that the total number of nodes connected to external pins is minimized.